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REFERENCES

- 1. MIPI Alliance Specification for D-PHY, Version 0.90.00 (October 8, 2007)
- 2. MIPI Alliance Specification for Display Serial Interface, Version 1.01.00 (February 21, 2008)
- 3. MIPI Alliance Specification for Display Bus Interface, Version 2.00 (November 29, 2005)
- 4. MIPI Alliance Specification for Display Pixel Interface(DPI-2), Version 2.00 (September 15, 2005)





1. Overview

TC358763XBG provides data conversion between multiple input formats to a specified output format for mobile display systems. As the middle-range to high-end mobile phone sets are going to integrate higher-resolution, wider color depth, and larger size display in the clam-shell style body, connection between base body and display system is getting more difficult

TC358763XBG supports MIPI DSI (Display Serial Interface) as a LCD interface. TC358763XBG also supports conventional LCD interface protocols; MIPI-DPI (Display Port Interface), MIPI-DBI (Display Bus Interface) as Host interface.

TC358763XBG can support 24-bit RGB Color format up to XGA size LCD module, when DPI is selected as Host interface. It also supports many different color format, and different LCD resolutions.

By using latest power saving technology, TC358763XBG can be controlled to minimize the power consumption in the target system.

Figure 1.1 shows the system overview and a block diagram of TC358763XBG.

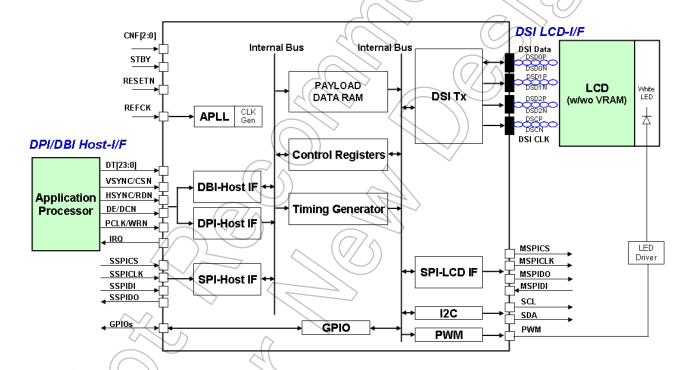


Figure 1.1 System Block Diagram of TC358763XBG

Pin Name Abbreviation:

GPIOs: GPIO0 to GPIO6



2. Features

- LCD module interface
 - MIPI DSI-TX Data 3-lane, CLK 1-lane with data rates up to 500Mbps/lane
 - ♦ Support up to XGA size LCD panel. (When DPI is selected as host interface)
 - ♦ Output format: RGB888, RGB666 and RGB565.
 - ♦ Maximum LCD resolution setting size: 1024 × 1024
- Host interface
 - ♦ MIPI DPI 24-bit bus interface
 - ♦ MIPI DBI Type-B 16-bit bus interface
 - ♦ Serial input interface
 - 3 or 4-wire 8-bit SPI synchronous transfer
 - 3-wire 9-bit SSI synchronous transfer
- Peripheral control ports
 - ♦ SPI or SSI serial I/F ports
 - ♦ Single I²C serial I/F port
 - ♦ Up to 13 General Purpose I/O ports
 - ♦ One PWM signals for LED intensity control
- PLL with 9.6MHz to 40MHz external reference clock to generate internal clock.
- Power supply
 - \Leftrightarrow Core: 1.2 V \pm 0.1 V
 - \Rightarrow DSI I/O: 1.2 V \pm 0.1 V
 - \Rightarrow I/O: 1.8 V \pm 0.1 V to 3.0 V \pm 0.3 V
- Package
 - ♦ 4.5mm×4.5mm body, 72 ball, 0.4mm ball pitch, 1.0mm height (max)





3. External Pins

3.1. Pin layout

Top Vie	₩							
A1	A2	A3	A4	A 5	A6	A7	A8	A9
VDDS	DT10	DT11	AVSS	AVSS	AVSS <	AVS8	ysso	VDDS
B1	B2	B3	B4	B5	B6	BA	B8	B9
VSSO	DT9	DE	AVDD18	AVSS	AVDD12	HSYNC	DT12	DT13
C1	C2	C3	C4	C5	C6	C7	C8	C9
POLK	STBY	DT8	GPIO1	GPIO3	(VSYNC)	GPIO0	DT14	VDDC
D1	D2	D3	D4	D5)D6	D7	D8	// D9
VDDC	DT7	CNF0	No ball	No ball	No ball	DT15	DT16	VSSC
E1	E2	E3	E4	E5	E6	(F7/\)	E8	E9
VSSC	DT6	GPIO4	No ball	No ball	No bai	GPIO2	CNF2	VSSO
F1	F2	F3	F4	> _{F5}	F6) 77	F8	F9
DT4	DT3	DT5	No ball	No ball	No ball	DT17	DT20	VDDS
G1	G2	G3	G4	G5 🦴	G6	G7	G8	G9
VSSO	DT2	GPIO5	SCL	DT21	DT18	DT19	SDA	REFOK
H1	H2		H4	(H5)	Н6	H7	H8	Н9
VDDS	DT1	DSDOP	DSCP	VDDDS12	DSD1P	DSD2P	RESETN	DT22
J1 <	∕∕ J2		J4/	J5	J6	J7	J8	J9
GPIO6	D10	DSDON	DSCN	VSSDS	DSD1 N	DSD2N	DT23	CNF1

Figure 3.1 Ball layout (TC358763XBG)



3.2. Signal Description

Table 3.1 shows the signal functionality of TC358763XBG.

Notation for Table 3.1;

- 1. "I/O" column shows direction of pin
 "I" means input pin. "O" means output pin. "I/O" means "Input / Output" pin.
 "NA" means "not applicable".
- 2. "Type" column shows the type of IO pin "CMOS" means "CMOS" type input or inout pin. "CMOS" inout supports drive current value selection from 1mA, 2mA, 3mA, and 4mA by register settings. "SMT" means "Schmitt" type input or inout pin with pull-up/down control. "SMT" inout is 2mA drive current. "OD" means "Open Drain" type input or inout pin. "P" means Power supply. "G" means Ground.
- 3. "Initial" column shows the initial setting after reset with STBY="H".

 "In" means "Input pin, without pull-up nor pull-up resistor". "PD" means "Input with internal pull-down".

 "PU" means "Input internal pull-up".

 "L" means "Low level output". "H" means "High level output", "Hi-Z" means "Hi-Impedance". "NA" means "not applicable". "NC" means "no connection". No connection pin should be open.

When STBY="L", all pin except for GPIO6, is Hi-Impedance state. GPIO6 is "PD" state even if STBY="L".

Note: Pull-up and Pull-down register is implemented by MOS Tr. They work as register only when IO power (VDDS) is supplied.





Table 3.1 Signal Functionality of TC358763XBG

Group	Pin Name	Ball	I/O	Тур.	Initial	Function	Note
1.01	CNF2	E8	I/O	SMT	In	I Cl made central pin Configure Heat Interface	
LSI Mode	CNF1	J9	I/O	SMT	In	LSI mode control pin, Configure Host Interface	*1
Wode	CNF0	D3	I/O	SMT	In	types	
Reset	RESETN	Н8	I/O	SMT	ln	System Reset Input L: Reset H: Operation	_
&	REFCK	G9	I/O	CMOS	In	System Clock Input	_
Clock	STBY	C2	I	CMOS	ln	Sleep Enable L: Standby H: Operation	_
	VSYNC	C6	I/O	CMOS	*4	This pin has multiple functions. DPI: VSYNC (Vertical synchronization signal) DBI Type B: CSN	_
	HSYNC	В7	I/O	CMOS	*4	This pin has multiple functions DPI: HSYNC (Horizontal synchronization signal) DBI Type B: RDN	_
DBI/DPI	DE	В3	I/O	CMOS	*5	This pin has multiple functions. DPI: DE (valid Data Enable) DBI Type B: DCN	_
	PCLK	C1	I/O	CMOS	*4	This pin has multiple functions. DPI: PCLK (Pixel Clock) DBI Type B: WRN	_
	DT[17:0]	-	I/O	CMOS	*5	Video Data. Bus width is selectable among 8, 16, 18 or 24 bits.	*2
	DT18	G6	I/O	CMOS	*5	This pin has multiple functions. DBI/DPI bus width select = 1: DT[18] DBI/DPI bus width select = 0: GPIO[7]	_
	DT19	G7	1/0	CMOS	*5	This pin has multiple functions. DBI/DPI bus width select = 1: DT[19] DBI/DPI bus width select = 0: GPIO[8]	_
	DT20	F8	I/O	CMOS	*5	This pin has multiple functions. DBI/DPI bus width select = 1: DT[20] DBI/DPI bus width select = 0: GPIO[9]	_
GPIO	DT21	G5	I/O	CMOS	*5	This pin has multiple functions. { DBI/DPI bus width select, GPIO10 Function Select} = {1, x}: DT[21] {0, 1}: IRQ {0, 0}: GPIO[10]	_
<	DT22	Н9	4/0	CMOS	*5	This pin has multiple functions. { DBI/DPI bus width select, GPIO11 Function Select} = {1, x}: DT[22] {0, 1}: PWM {0, 0}: GPIO[11]	-
	DT23	J8	I/O	CMOS	*5	This pin has multiple functions. { DBI/DPI bus width select, GPIO10 Function Select} = {1, x}: DT[23] {0, 1}: CLKOUT {0, 0}: GPIO[12]	_



GPIO	0 C7	I/O	SMT	*7	This pin has multiple functions. If CNF[2:0]=[001 or 010 or 011 or 100]:SSPICS else if GPIO0 Function Select [1:0] = [00]: GPIO0 [01]: IRQ [10]: PWM [11]: Reserved	
GPIO	1 C4	I/O	CMOS	*6	This pin has multiple functions. If CNF[2:0]=[001 or 010 or 011 or 100]:SSPICLK else if GPIO1 Function Select [1:0] = [00]: GPIO1 [01]: IRQ [10]: CLKOUT [11]: Reserved	
GPIO	2 E7	I/O	SMT	*7	This pin has multiple functions. If CNF[2:0]=[001 or 010 or 011 or 100]:SSPIDI else if GPIO2 Function Select [1:0] = [00]: GPIO2 [01]: IRQ [10]: TE [11]: Reserved	
GPIO	3 C5	I/O	CMOS	THE STATE OF THE S	This pin has multiple functions. If CNF[2:0]=[001 or 010 or 011 or 100] & Slave SPI CS bypass output enable = [1]:SSPICS bypass output else if {Master SPI Enable} = [1]: MSPICS (Master SPI Chip Select) else GPIO3 Function Select} = [00]: GPIO3 [01]: CLKOUT [10]: Host image write line end pulse output [11]: Reserved	-
GPIO	4 E3	Wo	CMOS	4	This pin has multiple functions. {Master SPI Enable, GPIO4 Function Select} = [0,00]: GPIO4 [0,01]: PWM [0,10]: HDE output [0,11]: Reserved [1,xx]: MSPICLK (Master SPI Clock)	
GPIO	5 G3	1/0	CMOS	L	This pin has multiple functions. {Master SPI Enable, GPIO5 Function Select} = [0,0]: GPIO5 [0,1]: IIRQ [1,x]: MSPIDOI (Master SPI Data Out/In)	



	GPIO6	J1	I/O	SMT	PD	This pin has multiple functions. If CNF[2:0]=[001 or 010 or 011 or 100] { If {Slave SPI 4-wire Enable, Slave SPI CS bypass output enable} = [0, 1]: SSPICS bypass output [1, x]: SSPIDO (Slave SPI Data Out) } else if {Master SPI Enable, Master SPI CS pin select, GPIO6 Function Select [2:0]} = [1, 1, xx]: MSPICS2 (Master SPI CS2) [1, 0, xx]: MSPIDI (Master SPI Data In) [0, x, 11]: IRQ [0, x, 10]: PWM [0, x, 01]: TE [0, x, 00]: GPIO6	
I2C	SCL	G4	0	OD	Hi-Z	I ² C Clock signal (Master)	
(master)	SDA	G8	I/O	OD	Hi-Z	I ² C Data signal (Master)	
	DSD0P	H3	I/O	NA	NA	DSI Data Lane 0 Positive Input/Output	
	DSD0N	J3	I/O	NA	NA	DSI Data Lane 0 Negative Input/Output	
DSI	DSD1P	H6	0	NA	NA	DSI Data Lane 1 Positive Output	
special	DSD1N	J6	0	NA	NA	DSI Data Lane 1 Negative Output	_ <u>*1</u>
I/O	DSD2P	H7	0	NA	NA (DSI Data Lane 2 Positive Output	'
"	DSD2N	J7	0	NA	NA (DSI Data Lane 2 Negative Output	
	DSCP	H4	0	NA	ŅĄ	DSI Clock Positive Output	
	DSCN	J4	0	NA	NA	DSI Clock Negative Output	
	VDDC	-	-	Р (NA)	VDD for Internal Core(1.2 V)	
	VDDS	-	-	P	NA)	VDD for I/O	
	VDDDS12	H5	-	Đ)	NA	VDD for DSI Analog (1.2 V)	
	VSSDS	J5	-	G	NA	VSS for DSI	
Power &	AVDD12	В6	-(P	NA	Internal Analog core Power Please connect to AVSS	*3
Ground	AVDD18	В4)-\\\		NA	Internal Analog core Power Please connect to AVSS	
	AVSS	(-	//	7 G	NA	VSS for Internal Analog Core	
	VSSC	-/	<u> </u>	G /-	NA NA	Ground for Internal Core	
	VSSO	-	\rightarrow	G	NA	Ground for I/O	





*1: CNF[2:0] pin is used for Operation mode configuration of TC358763XBG. LCD Interface Configuration is specified by register settings. Initial State will change by the CNF[2:0] setting.

Table 3.2 CNF[2:0] Host I/F Configuration (LSI Mode)

_							
ONE (O.O.)	LOLMada	Host I/F		Initial	State		Maria
CNF[2:0]	LSI Mode	Configuration	*4	*5	*6	*7	Note
000	-	Reserved	-	-	-	- /	LSI Test mode
001	-	Reserved	-	-	- <	- (LSI Test mode
010	-	Reserved	-	-	-	7-/	LSI Test mode
011	Mode 2-1	DPI + SPI slave	In	In	In	(In	_
100	Mode 2-2	DPI + SSI slave	In	In	In	(g) -)~
101	Mode 3	DBI Type-B	In	In	4	PD.	-
110	-	Reserved	-	-	4	\nearrow	LSI Test mode
111	-	Reserved	-	-/		\ -	LSI Test mode

*2: DT[23:0] pin assignment

Table 3.3 DT[23:0] pin assignment

DT	Loc	DT	Loc	DT	Loc	DT	Loc	DT	Loc	DT	Loc
[23]	J8	[19]	G7	[15]	D7	[~] [11] ,	//A3	/[\]	D2	[3]	F2
[22]	H9	[18]	G6	[14]	Ç8	[10]	A2	[6]	E2	[2]	G2
[21]	G5	[17]	F7	[13]	В9	[9]	B2	√ <u>[</u> 5]	F3	[1]	H2
[20]	F8	[16]	D8	[12]	B8	[8]	C3	[4]	F1	[0]	J2

*3: VDD/VSS pin assignment

All VSS pins (VSSDS, VSSC, VSSO and AVSS) have to be connected to Ground. DSI analog power supply pin have to connect 1.2 V power supply for both with/without DSI use case.

Table 3.4 VDD/VSS pin assign

	Name	7		Pin			Function
	VDDC	<u>C</u> 9	D1	.(/-	-	-	VDD for Internal Core
Ţ	VDDS	A1	A9 [₹]	TF9	H1	J5	VDD for I/O
	VSSC	D9	E/	/-/	-	-	VSS for Internal Core
	VSSO	A8/	B1	<u>E</u> 9	G1	-	VSS for I/O
1	AVSS	B5	/A4\	A5	A6	A7	VSS for Internal Analog Core

*A4, A5, A6, A7 can be tied to GND or can be left open.

DT16 to DT23: GND SDA and SCL: GND GPIO3 to GPIO6: Open

DSD1P, DSD1N, DSD2P, DSD2N: Open

GPIO0 to GPIO2: Open (Mode3 (CNF[2:0]=101) only)

^{*4} to *7: Refer to Initial state field of Table 3.2.

^{*8:} If signals are not used, please connect as follows.



4. Package

4.1. Package Dimensions (P-VFBGA72-0404-0.40A3)

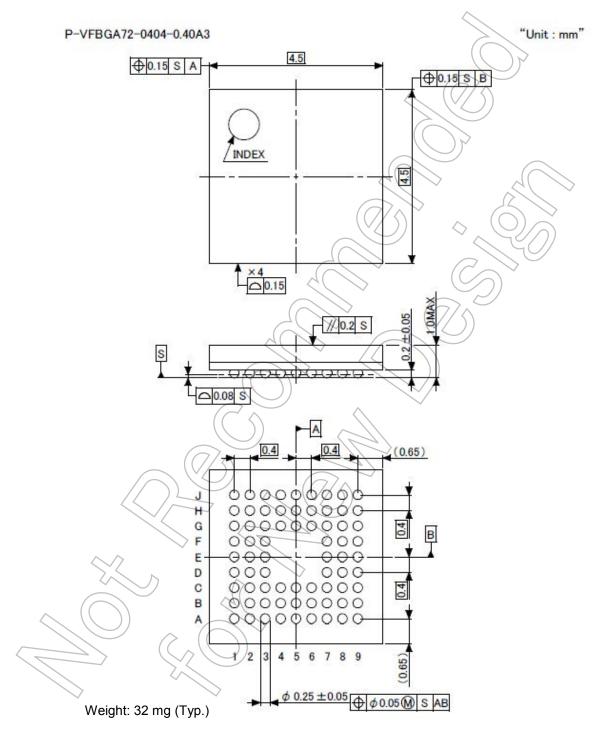


Figure 4.1 Package Dimensions of TC358763XBG



5. Electrical Characteristics

5.1. Absolute Maximum Ratings

VSS= 0V reference

Table 5.1 Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
	VDDS	-0.3 to +3.9	V
Power Supply voltage	VDDDS12	-0.3 to +1.8	V
	VDDC	-0.3 to +1.8	V
Input voltage	VIN	-0.3 to VDDS+0.3	V
Output voltage	VOUT	-0.3 to VDDS+0.3	V
Input Current	IIN	-10 to +10	mA
Storage temperature	Tstg	-40 to +125	√ °C

5.2. Operating Condition

VSS= 0V reference

Table 5.2 Operation Condition

Parameter	Symbol	Min	Typ.	Max	Unit
	VDDS)) 1.7	//	3.3	
Power Supply voltage	VDDDS12	1.1	1.2	1.3	V
	VDDC)	1.1	1.2	1.3	
Operating frequency (internal system clock)	Fopr	-	_	125	MHz
Operating temperature	ta	-20	-	+85	°C



6. Revision History

Table 6.1 Revision History

Revision	Date	Description
1.60g	2014-04-10	Newly released
1.61	2016-04-01	Package's weight is rounding up digits after the decimal point to form an integer.
1.71	2017-11-09	Corrected *2 in section 3.2. Changed header, footer and the last page. Changed corporate name.





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